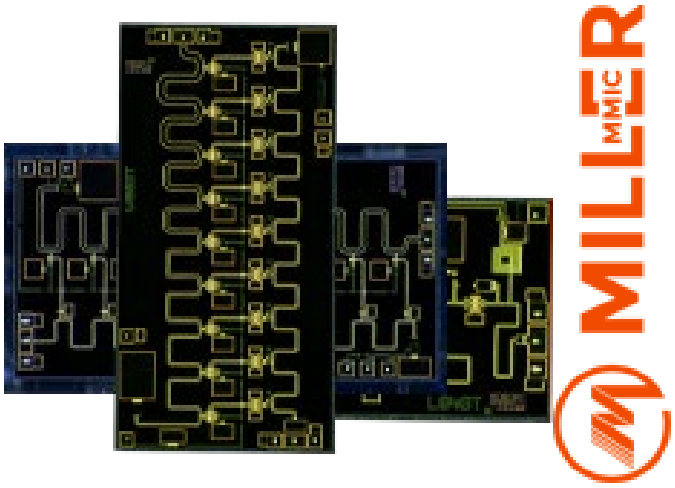
Features

- Ultra broadband three channel attenuator
- Frequency Range: DC - 40GHz
- 3 Channels with 3 different Attenuation value
- Power Handling: 27dBm
- 50Ω Input and Output Impedance
- Return Loss: 20dB
- Bare Die (QFN Available)
- RoHS & REACH Compliant

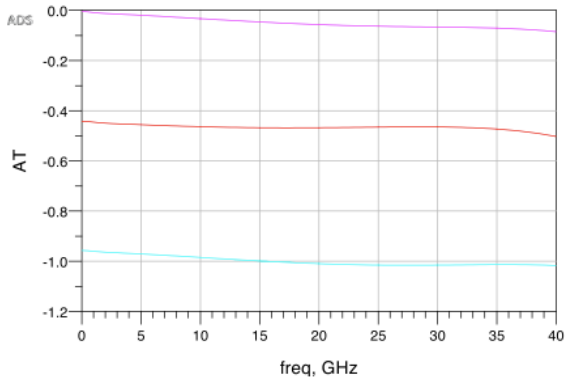


Typical Applications

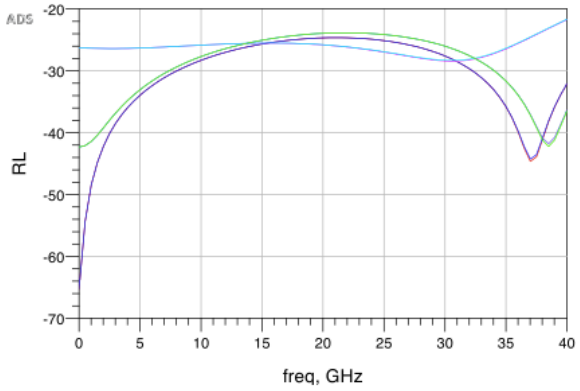
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- General Purpose

Part Number	Product Description	Frequency (GHz)	Channel	Attenuation (dB)	Power (dBm)	Flatness (dB)	VSWR
MFA1015	3 Channel Fixed Attenuator	DC-40	3	0/0.5/1	27	±0.3	1.22
MFA1016	3 Channel Fixed Attenuator	DC-40	3	0/1/2	27	±0.3	1.22
MFA1017	3 Channel Fixed Attenuator	DC-40	3	0/2/4	27	±0.3	1.22
MFA1018	3 Channel Fixed Attenuator	DC-40	3	0/3/5	27	±0.3	1.22
MFA1019	3 Channel Fixed Attenuator	DC-40	3	1/2/3	27	±0.3	1.22

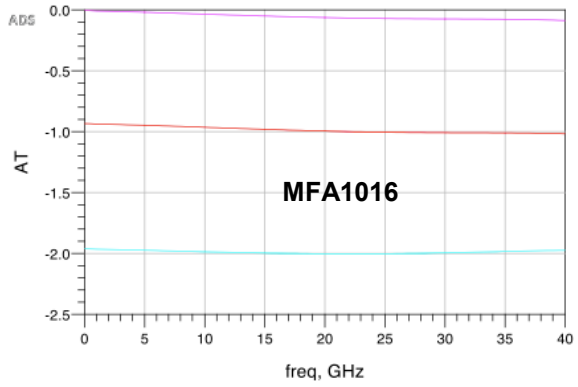
MFA1015

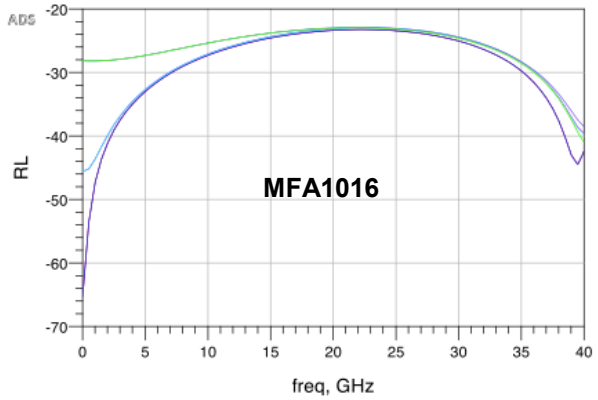


MFA1015



MFA1019
GaAs MMIC Three Channel Series Fixed Attenuator DC-40GHz


ADS
AT
MFA1016
freq, GHz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RL
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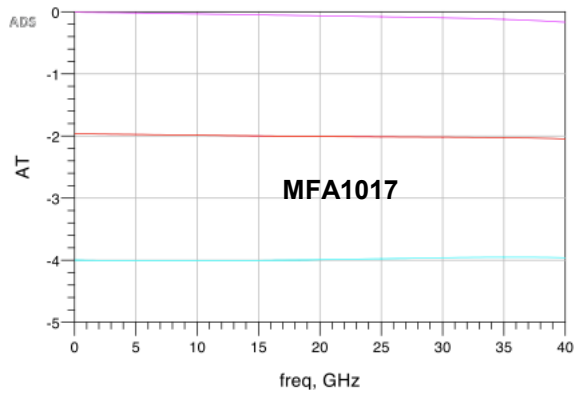
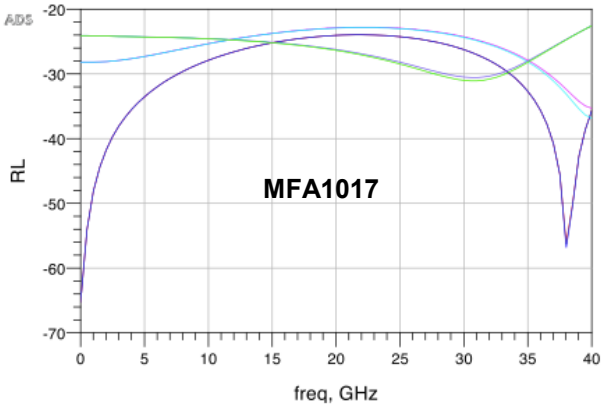
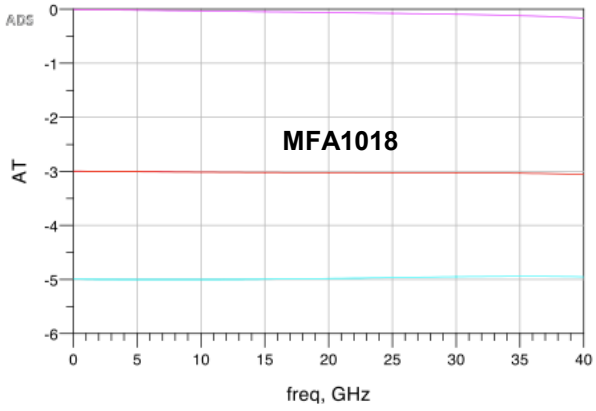
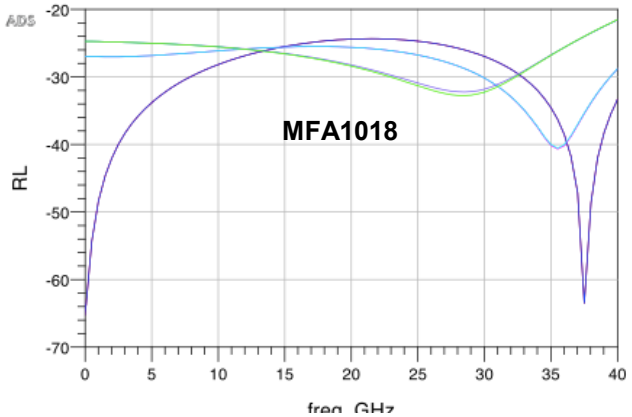
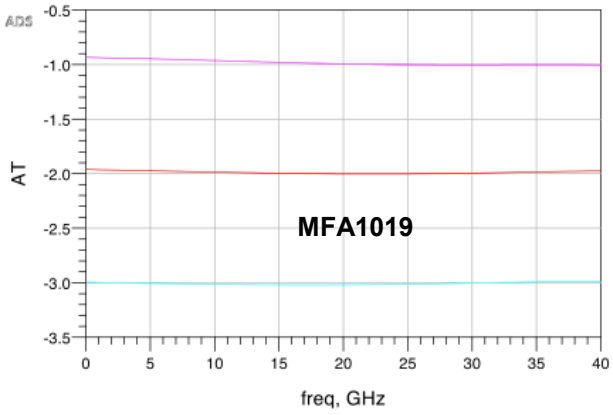
freq, GHz

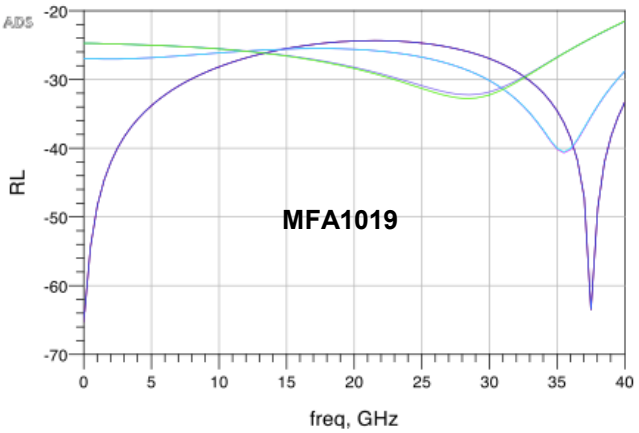

ADS
AT
MFA1017
freq, GHz


ADS
RL
MFA1017
freq, GHz


ADS
AT
MFA1018
freq, GHz


ADS
RL
MFA1018
freq, GHz

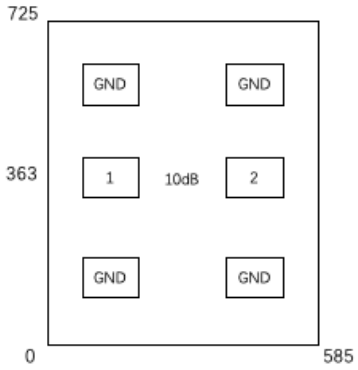

ADS
AT
MFA1019
freq, GHz


ADS
RL
MFA1019
freq, GHz

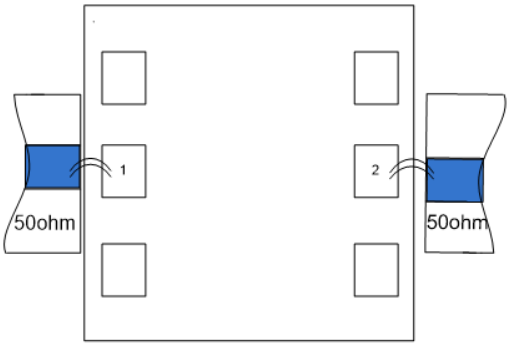
Outline Drawing:

All Dimensions in μm

Pad	Function	Description
1	RF IN	RF signal input terminal; DC blocking capacitor required.
2	RF OUT	RF signal output terminal; DC blocking capacitor required.
Die bottom	GND	Die bottom must be connected to RF/DC ground.



Assembly Drawing



Notes:

1. Die thickness: 100μm
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum input power: +27dBm
2. Operating temperature: -55℃ to +85℃
3. Storage temperature: -65℃ to +150℃